

# 7/B  
w/ Drawing 6/26/03  
END919970013US2  
Mollini

Appln. No. 10/001,421  
Amendment Dated June 17, 2003  
Reply to Office Action of May 21, 2003



Appln. No:  
Applicants:  
Filed:  
Title:  
TC/A.U.:  
Examiner:  
Confirmation No.:  
Docket No.:

10/001,421  
Joseph M. Milewski et al.  
November 2, 2001  
LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE  
2811  
Hung K. Vu  
4204  
END919970013US2  
**AMENDMENT**

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action dated May 21, 2003, please amend the above-identified application as follows:

- ☒ **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.
- ☒ **Amendments to the Drawings** begin on page 3 of this paper and include an attached replacement sheet.
- ☒ **Remarks/Arguments** begin on page 4 of this paper.

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JUN 20 2003  
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